



IFW

PATENT
Docket No. 20063/OG03-051

IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE

Applicant(s):

Seung Jong Yoo

U.S. Serial No.: 10/747,603

For: "Methods of Fabricating
Semiconductor Device Bonding
Pads"

Filed: 12/29/2003

Group Art Unit: 2812

Examiner: Not Yet Assigned

- I hereby certify that this paper and the documents referred to as enclosed therewith are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on this date:
- June 24, 2005**
- 
- Mark C. Zimmerman**
- Attorney for Applicant(s)
- Registration No. 44,006

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Kindly advise when an Office action can be expected in the above-referenced matter.

Respectfully submitted,

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June 24, 2005

By:


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